# 2D Materials for Energy Harvesting Applications and the Scaling-up Route

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#### **RWTH Aachen University**

- Large European Technical Univ.
- 50.000 students
- Triangle:

Germany / Belgium / Netherlands

Chair of Electronic Devices



#### AMO GmbH

- High-Tech SME / Institute (non-profit) / Research Foundry
- 400 m<sup>2</sup> clean room
- 80 staff members in 35 funded R&D projects
- > 100 R&D partners across Europe and beyond
- Silicon technology, Nanofabrication & New Materials
  - Targeted applications
    - Nanoelectronics, Sensors, Flexible Electronics
    - Nanophotonics
    - Quantum Technologies
    - Neuromorphic Computing
    - Environmental Nanotechnology
- Mission: Technology Transfer
  - R&D Partners & Start Ups (Black Semiconductor, Protemics, AMOtronics)







#### **Graphene: Crystal Properties**



- sp<sup>2</sup> bonded carbon atoms (~4,3eV)
- Graphite: stacked layers of graphene
- interlayer bond: v.d. Waals





- Lattice constant: a = 0.246 nm
- "Thickness": d = 0.34 nm















Year of 1<sup>st</sup> introduction

6



Lemme et al., Nat. Comm., 2022



#### imec 20-Year Semiconductor Roadmap









## More Moore

- 2D Nanosheet FETs
  - Ultimate electrostatic control
  - No loss of mobility
  - − BEOL integration  $\rightarrow$  3D



Source: IMEC

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https://www.imec-int.com/en/articles/imec-introduces-2dmaterials-logic-device-scaling-roadmap



Radosavlevic et al., IEEE Spectrum, 2022







#### **2D-Integration: Opportunities**







#### Graphene and 2D materials:

- + Ultra broad band spectral response (graphene, PtSe<sub>2</sub>)
- + Large scale production (CVD)
- + High conductivity
- + mechanical Flexibility
- + Integrability
- $\pm$  Gate tunability
- Low absolute absorption









#### Graphene /silicon Schottky diodes

- Vertical Schottky diode architecture
- High responsivity
- Ease of Integration
- Potential for infrared detection
- Potential for flexible substrates



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Riazimehr *et al.*, SSE, 2016 Riazimehr *et al.*, ACS Photonics, 2017 Riazimehr *et al.*, ACS Photonics, 2019







Graphene

Cr/Au

Cr/Au

SiO<sub>2</sub>

Si

#### Graphene / silicon Schottky diodes

- Vertical device architecture
- High responsivity
- Ease of Integration
- Potential for infrared detection
- Potential for flexible substrates
- Shockley equation:

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$$I = I_S[\exp\left(\frac{qV_d}{nk_BT}\right) - 1]$$

- Ideality factor n =1.52
- Barrier height  $Ø_b = 0.66 \text{ eV}$
- p doping due to exposure to ambient atmosphere













2D Materials Center



- Interdigitated diode layout
- Very high spectral response / maximum responsivity (635 mA/W) ightarrow 1.5x pure Si
- Very high quantum efficiency (>80%)
- Enabled by inversion channel under MOS structure







#### **Graphene / Quantum Dot Integration for IR Photodetection**





#### Rectennas

- High RF-to-DC conversion efficiency demonstrated with monochromatic MHz-GHz sources (>90% at 2.45 GHz)
- Bottleneck in adapting to higher frequencies: response time of the rectifier
- Metal-insulator-metal diodes
  - Fast response time due to majority charge carrier transport
  - Usually low responsivity, low rectification efficiency
- Metal-insulator-graphene diodes
  - Enhanced responsivity
  - Reduced junction capacitance increases frequency response

Sinohara, River Publishers **2017** Hemmetter et al., ACS Applied Electronic Materials **2021** 









#### **Ballistic Rectification**

- **Ballistic rectifier** 
  - Charge carrier scattering occurs primarily at the device edges
  - No potential barrier inhibits current  $\rightarrow$  zero-bias operation
- Two-terminal and four-terminal devices have been demonstrated
  - GaAs-AlGaAs and InAs/AlGaSb heterostructures
  - Si nanowires
  - graphene
- Long mean free path requires high charge carrier mobility

Passi et al., 2017 Silicon Nanoelectronics Workshop, 2017 Song et al., Phys. Rev. Lett. 1998 White et al., ACS Applied Nano Materials 2023 Auton et al., Nat Communications 2016









#### **Ballistic Transport in Graphene**

- Graphene: mobility up to 350,000 cm<sup>2</sup>/Vs
  - On insulating substrates
  - At room temperature
  - With scalable material growth techniques (CVD)
- Mean free path > 28μm in CVD graphene
- Ballistic reflection especially important at the graphene edge





Banszerus *et al., Nano Letters* 2016 Banszerus *et al., Sci. Adv.* 2015 De Fazio *et al., ACS Nano*, 2019







#### **2D-CMOS Integration: Challenges**



Neumaier, Pindl, Lemme, Nature Materials, 2019 Akinwande *et al.*, Nature, 2019 Illarionov *et al.*, Nature Communications, 2020 Quellmaltz *et al.*, Nature Communications, 2021 Lemme *et al.*, Nature Communications, 2022

#### Growth

- Catalytic CVD on metals
- Temperatures: 400-1000°C
- Quality

#### **Transfer process**

- Quality
- Automation

#### Etching

• Etch stop  $\rightarrow$  ALE

#### Encapsulation

• ALD vs. 2D

#### **Electrical contacts**

- ✓ Graphene
- Semiconducting 2D



A number of Engineering Challenges remain before we see 2D Materials-based electronics / optoelectronics





#### Chemical vapor deposition (CVD)



- Catalytic growth on Ni, Cu, Ru, Ir, TiC, Ta...
- + Process Temperatures: 850-1000°C
- + Transfer to random substrates
- Transfer process
- + High potential for large areas (R2R)
- Monolayer vs. multilayer control (solubility)
- Quality (grain boundaries, defects etc.) S. Kataria et al., physica status solidi (a), 2014., 2014









Etching method	Bubble method	Capillary method
Chemical process	Electrochemical process	Physical process (Capillary effec
Copper is etched away	Copper is removed by bubbles created at the interface	Copper is removed by water between copper and graphene
Etchant: FeCl <sub>3</sub> , Sodiumpersulfa	t∉lectrolyte: NaOH	Reactant: DI-Water
Duration: 1h 30min	Duration: 30s	Duration: 8h
Max Lemme	Aachen Graphene & 2D Materials Center	



#### Integration challenge: contamination

- Time-of-flight secondary ion mass spectrometry (ToF-SIMS) and
- Total reflection x-ray fluorescence (TXRF) →
  - Elemental fingerprints of residual contamination with a sensitivity better than 10<sup>9</sup> atoms/cm<sup>2</sup>.



ToF SIMS <sup>63</sup>Cu<sup>+</sup> and <sup>56</sup>Fe<sup>+</sup> maps on the corner of a graphene layer on SiO<sub>2</sub>

















#### **European 2D Experimental Pilot Line**

- H2020 project to develop technology (not a specific application)
- Start in 10/2020, 4 years, 20 M€ funding
- Goal: technology transfer to Europractice and European Industry

### 1. Development of tools & materials





Industrial Advisory Board		
X-FAB		
AMS		
NXP		
Infineon		
STMicroelectronics		
Emberion		
Nokia		
ELMOS		







#### **European 2D Experimental Pilot Line**



Development of tools, modules and platforms in parallel with the offer of MPW runs.

28







European Commission

### **The 2D Experimental Pilot Line**

#### Multi-Project Wafer Run #1



#### **Overall applications**



#### 35 applications => 14 participating customers

















Aalto-yliopisto



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#### More information is available at www.greenergy-project.eu







